

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
1	BRS	L1	2	"6350673"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 17:41			
2	BRS	L2	59	(interconnect\$5 or metal) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:03			
3	BRS	L3	69	(interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:21			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
4	BRS	L5	0	(438/225).ccls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:06			
5	BRS	L6	0	(438/287).ccls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:05			

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6	BRS	L7	2	(438/958).cccls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:05			
7	BRS	L8	0	(438/255).cccls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:06			

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8	BRS	L9	0	(257/E21.252).c cls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:06			
9	BRS	L10	0	(257/E21.627).c cls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:07			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
10	BRS	L11	0	(257/E21.614).c cls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:07			
11	BRS	L12	3	(257/E21.279).c cls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:09			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ro r De fi ni ti on	Er ro rs
12	BRS	L13	20	(257/E21.\$).ccl s. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:12			
13	BRS	L14	24	("438"/\$).ccls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:12			
14	BRS	L15	40	("4113514" "4181751").PN. OR ("4331709").URP N.	US-PGPUB; USPAT; USOCR	2006/08/20 19:14			

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15	BRS	L4	4	(438/619-662).ccls. and (interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:16			
16	BRS	L16	1	(438/619-662).ccls. and (interconnect\$5 or metal or via or plug) and semiconductor and (hydrogen or h2 or "h.sub.2") near diffus\$5 with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:17			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17	BRS	L17	8	(interconnect\$5 or metal or via or plug) and semiconductor and (hydrogen or h2 or "h.sub.2") near diffus\$5 with saturat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:19			
18	BRS	L18	9	(interconnect\$5 or metal or via or plug) and semiconductor and (hydrogen or h2 or "h.sub.2") with diffus\$5 with saturat\$5 with bond	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:20			
19	BRS	L19	11	(interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5 with (bond or chc)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:25			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
20	BRS	L20	1	(interconnect\$5 or metal or via or plug) and semiconductor with (hydrogen or h2 or "h.sub.2") with saturat\$5 with chc	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:25			
21	BRS	L21	1	(interconnect\$5 or metal or via or plug) and semiconductor and (hydrogen or h2 or "h.sub.2") with saturat\$5 with chc	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:26			
22	BRS	L22	1	semiconductor and (hydrogen or h2 or "h.sub.2") with saturat\$5 with chc	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:27			
23	BRS	L23	27	(hydrogen or h2 or "h.sub.2") with saturat\$5 with chc	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:26			

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24	BRS	L24	3	semiconductor and (hydrogen or h2 or "h.sub.2") with saturat\$5 same chc	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:27			
25	BRS	L25	16	semiconductor and (hydrogen or h2 or "h.sub.2") with saturat\$5 and chc	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/08/20 19:27			